



Re-classification of VOG8 Moisture Sensitivity Level

XCN06001 (v1.1) March 2, 2006

Customer Notice – FYI

Overview

The purpose of this notification is to communicate that subjecting the VOG8 package to MSL 1 might cause some delamination on the bond fingers of the lead frame (<10% delamination). The delamination will not cause any electrical failure after pre-conditioning and no long-term reliability failures.

Qualification data for this package using MSL 3 showed no delamination on the bond fingers. The MSL of this package is therefore being re-classified from MSL 1 to MSL 3 per JEDEC STD-020C.

Description

Moisture-induced delamination on the bond fingers has been observed on the VOG8 package after MSL 1 pre-conditioning. The delamination will not cause any electrical failure after pre-conditioning and no long-term reliability failures.

The VOG8 package that was subjected to MSL 3 pre-conditioning did not show any bond finger delamination. The pre-conditioning was performed per JEDEC STD-020C conditions (192 hours of moisture soaking at 30°C / 60% RH followed by 3X IR reflow at the pb-free peak reflow temperature of 260°C).

Re-classification of this package as MSL 3 means that these devices will have a limited floor lifetime of 168 hours.

Products Affected

This change affects all speed, package, and temperature variations of the commercial (C) and industrial (I) grade devices. Automotive and Q grade devices are not affected by this Notice. The affected part numbers are included in [Table 1](#).

Table 1: Products Affected

Devices	
XC1736EVOG8C	XC17S200AVOG8C
XC17128EVOG8C	XC17S10XLVOG8C
XC1765ELVOG8C	XC17S10XLVOG8I
XC17S15AVOG8C	XC17S20XLVOG8C
XC17S50AVOG8C	XC17S30XLVOG8C
XC17S100AVOG8C	

Recommendations

Mount the devices on PCB boards within 168 hours after moisture barrier bags are opened (refer to JEDEC-STD-020C).

Response

No response is required. For additional information or questions, please contact [Xilinx Technical Support](#).

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Revision History

The following table shows the revision history for this document.

Date	Version	Revision
01/16/06	1.0	Initial Xilinx release.
03/02/06	1.1	Updated Table 1 with the complete part numbers that include the “C” and “I” part designators.